N-CHANNEL ENHANCEMENT MOS FET

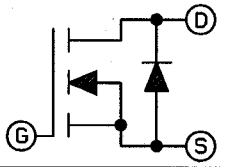
200V, 9A, 0.415Ω

SDF230 JAA
SDF230 JAB
SDF230 JDA

FEATURES

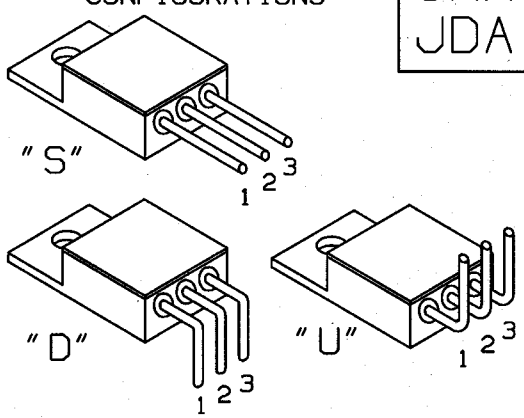
- RUGGED PACKAGE
- HI-REL CONSTRUCTION
- CERAMIC EYELETS: JAA, JAB
- LEAD BENDING OPTIONS
- COPPER CORED 52 ALLOY PINS
- LOW IR LOSSES
- LOW THERMAL RESISTANCE
- OPTIONAL MIL-S-19500 SCREENING

SCHEMATIC



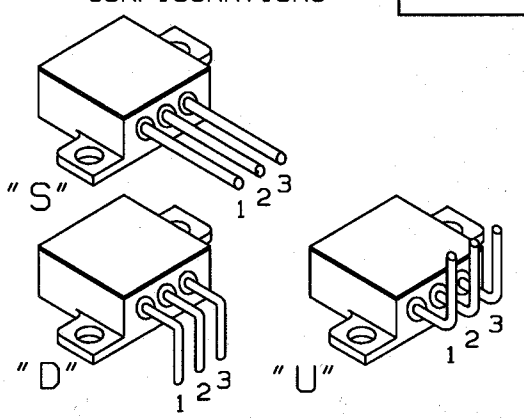
TERMINAL CONNECTIONS			
G		H	
1	GATE	1	DRAIN
2	DRAIN	2	SOURCE
3	SOURCE	3	GATE

STANDARD BEND CONFIGURATIONS — JAA JDA



(CUSTOM BEND OPTIONS AVAILABLE)

STANDARD BEND CONFIGURATIONS — JAB



(CUSTOM BEND OPTIONS AVAILABLE)

REV. 10/93

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL		UNITS
Drain-source Volt.(1)	VDSS	200	Vdc
Drain-Gate Voltage (R_{GS}=1.0MΩ) (1)	VDGR	200	Vdc
Gate-Source Voltage Continuous	VGS	±20	Vdc
Drain Current Continuous (Tc = 25°C)	ID	9.0	Adc
Drain Current Pulsed(3)	IDM	36	A
Total Power Dissipation	PD	75	W
Power Dissipation Derating > 25°C		0.6	W/°C
Operating & Storage Temp.	TJ/Tsig	-55 TO +150	°C
Thermal Resistance	RthJc	1.7	°C/W
Max.Lead temperature	TL	300	°C

ELECTRICAL CHARACTERISTICS T_C = 25°C (UNLESS OTHERWISE SPECIFIED)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Drain-source Breakdown Volt.	V(BR)DSS	VGS=0V ID=250 µA	200	–	–	V
Gate Threshold Voltage	VGS(TH)	VDS=VGS ID=250 µA	2.0	–	4.0	V
Gate Source Leakage	IGSS	VGS=±20 V	–	–	100	nA
Zero Gate Voltage Drain Current	IDSS	VDS=MAX. RATING VGS=0	–	–	250	µA
		VDS=0.8 MAX. RATING VGS=0 TJ=125°C	–	–	1000	µA
Static Drain-Source On-State Resistance(1)	RDS(ON)	VGS=10 V ID=5.0A	–	–	.415	Ω
Forward Trans-Conductance (2)	gfs	VDS ≥ 50 V IDS=5.0A	3.0	–	–	S(℧)
Input Capacitance	CISS	VGS=0V VDS=25 V f=1.0 MHz	–	650	–	pF
Output Capacitance	COSS		–	250	–	pF
Reverse Transfer Capacitance	CRSS		–	80	–	pF
Turn-On Delay	td(on)	VDD=90V RG=12Ω ID=5.0A RD=15Ω (MOSFET switching times are essentially independent of operating temp.)	–	–	30	ns
Rise Time	tr		–	–	50	ns
Turn-Off Delay	td(off)		–	–	50	ns
Fall Time	tf		–	–	40	ns
Total Gate Charge (Gate-Source Plus Gate-Drain)	Qg	VGS=10V, ID=12A VDS=0.8 MAX. RATING (Gate charge is essentially independent of the operating temperature)	–	19	30	nC
Gate-Source Charge	Qgs		–	10	–	nC
Gate-Drain ("Miller") Charge	Qgd		–	9	–	nC

SOURCE-DRAIN DIODE RATINGS & CHARACT. T_C = 25°C (UNLESS OTHERWISE SPECIFIED)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Continuous Source Current (Body Diode)	IS	Modified MOSFET symbol showing the integral reverse P-N junction rectifier (See schematic)	–	–	9.0	A
Pulse Source Current (Body Diode) (1)	ISM		–	–	36	A
Diode Forward Voltage (2)	VSD	IF=9.0A VGS=0V T_C=+25°C	–	–	2.0	V
Reverse Recovery Time	trr	T_C=+25° C IF=9.0A di/dt=100A/µS	–	450	–	ns
Reverse Recovery Charge	Qrr		–	3.0	–	µC

(1) TJ = 25°C to 150°C.
(2) Pulse test: Pulse Width < 300µS, Duty Cycle < 2%.
(3) Repetitive Rating: Pulse Width limited By Max. junction Temperature.